

N-Channel Enhancement Mode Power MOSFET

Description

The MSF6N65 is a N-channel enhancement-mode MOSFET , providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220F package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance
- · Simple Drive Requirement
- · Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Application

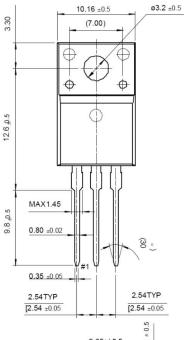
- Open Framed Power Supply
- Adapter
- STB

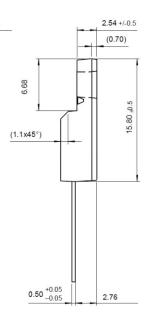
Packing & Order Information

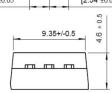
50/Tube ; 1,000/Box



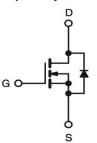








Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings						
Symbol	Parameter	Value	Unit			
V _{DSS}	Drain-Source Voltage	650	V			
V _{GS}	Gate-Source Voltage	±30	V			
I _D	Drain Current -Continuous (TC=25°C)	6.0	A			
	Drain Current -Continuous (TC=100°C)	3.6	A			
I _{DM}	Drain Current Pulsed	24	A			
I _{AR}	Avalanche Current	6.0	A			
E _{AS}	Single Pulsed Avalanche Energy	135	mJ			
E _{AR}	Repetitive Avalanche Energy	5.4	mJ			
dv/dt	Peak Diode Recovery dv/dt	4.5	V/ns			



N-Channel Enhancement Mode Power MOSFET

Absolute Maximum Ratings						
Symbol	I Parameter Value					
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C			
TPKG	Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C			
P _D	Total Power Dissipation (TC = 25 °C)	54	W			
	Derating Factor above 25 °C	0.3	W/°C			
T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C			
TJ	Storage Temperature	150	°C			

Notes;

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. I_{AS} =7A, V_{DD} =50V, L=7mH, V_{G} =10V, Starting T_J=25°C

3. I_{SD} \leq 7A, di/dt \leq 200A/µs,V_{DD} \leq BV_{DSS}, Starting T_J=25°C

Thermal Characteristics					
Symbol	Parameter	Max.	Units		
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction-to-Case	2.3	°C/W		
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/w		

Static Characteristics						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 V$, $I_D = 250 \mu A$	600			V
ΔBV_{DSS}	Breakdown Voltage	$I_{D} = 250 \mu A$, Referenced to 25°C		0.65		V/°C
$/\Delta T_J$	Temperature Coefficient	$I_{\rm D} = 200 \mu \Lambda$, Referenced to 20 C		0.05		V/C
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS} , I_D = 250 \mu A$	2.0		4.0	V
	Zero Gate Voltage Drain	$V_{DS} = 650 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
I _{DSS}	Current	$V_{DS} = 540 \text{ V}$, $T_{C} = 125^{\circ}\text{C}$			10	
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 30$			±100	nA
1655	Forward					
R _{DS(ON)}	Static Drain-Source	$V_{GS} = 10 \text{ V}$. $I_{D} = 3.0 \text{ A}$		1.23	1.5	Ω
	On-Resistance	VGS = 10 V, 10 = 3.0 A		1.20	1.5	

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
Qg	Total Gate Charge	$V_{DS} = 520 \text{ V}, I_D = 6 \text{ A},$ $V_{GS} = 10 \text{ V}$		19		nC
Q _{gs}	Gate-Source Charge			5.1		nC
Q _{gd}	Gate-Drain Charge			6.9		nC



N-Channel Enhancement Mode Power MOSFET

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
t _{d(on)}	Turn-On Time	$V_{DS} = 325 \text{ V}, \text{ I}_{D} = 6 \text{ A},$ $R_{G} = 25 \Omega, V_{GS} = 10 \text{ V}$		12		ns
t _r	Turn-On Time			13		ns
t _{d(off)}	Turn-Off Delay Time			25		ns
tf	Turn-Off Fall Time			13		ns
C _{ISS}	Input Capacitance			1350		pF
C _{OSS}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0MHz		120		pF
C _{RSS}	Reverse Transfer Capacitance			26		pF

Source-Drain Diode						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
ls		$V_{\rm D} = V_{\rm G} = 0$			6.0	A
I _{SM}		$V_{\rm D} = V_{\rm G} = 0$ $V_{\rm S} = 1.3 \text{ V}$			24	
V _{SD}		$I_{S} = 6 \text{ A}$, $V_{GS} = 0 \text{ V}$			1.5	V
t _{rr}		$I_{F} = 6 \text{ A}$, $V_{GS} = 0 \text{ V}$		330		ns
Q _{rr}		diF/dt=100A/µs		2.8		μC

Notes;

1. Pulse Test: Pulse Width ≦ 300µs, Duty Cycle≦ 2%



N-Channel Enhancement Mode Power MOSFET

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE. Bruckewell Technology Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Bruckewell"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product. Bruckewell makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Bruckewell disclaims

- (i) Any and all liability arising out of the application or use of any product.
- (ii) Any and all liability, including without limitation special, consequential or incidental damages.

(iii) Any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Bruckewell's knowledge of typical requirements that are often placed on Bruckewell products in generic applications.

Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time.

Product specifications do not expand or otherwise modify Bruckewell's terms and conditions of purchase, including but not limited to the warranty expressed therein.